



Emerging Trends in Dielectric Materials for Science and Technology

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Message from the Guest Editor

Dear Colleagues,

Modern challenges of ecology, resource efficiency, and environmental issues place stricter demands for dielectric materials research. Many efforts have been invested in producing environmentally friendly materials to be more cost-effective, consume less energy, and consume fewer resources. Materials representing traditional dielectric films used in semiconductor devices, especially oxides and nitrides, are replacing studies with new methods on materials with unique dielectric responses.

This Special Issue of Materials aims to provide a collection of papers focusing on modern trends in dielectric materials, new approaches to structuring environmentally friendly materials, and new ways to optimize material parameters concerning a variety of technology-oriented applications.

The topics of interest include, but are not limited to metals, ceramics, ferroelectrics, glasses, polymers, electrical and electronic materials, composite materials, microwave absorbers, multilayer structure dielectrics, fibers, nanostructured materials, low and high dielectric constant materials, nano-fluids, and materials for application in the life sciences.





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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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